# Cost Comparison between Different 4PPoE Implementations

Kousi Balasubramanian John Wilson Sesha Panguluri David Abramson

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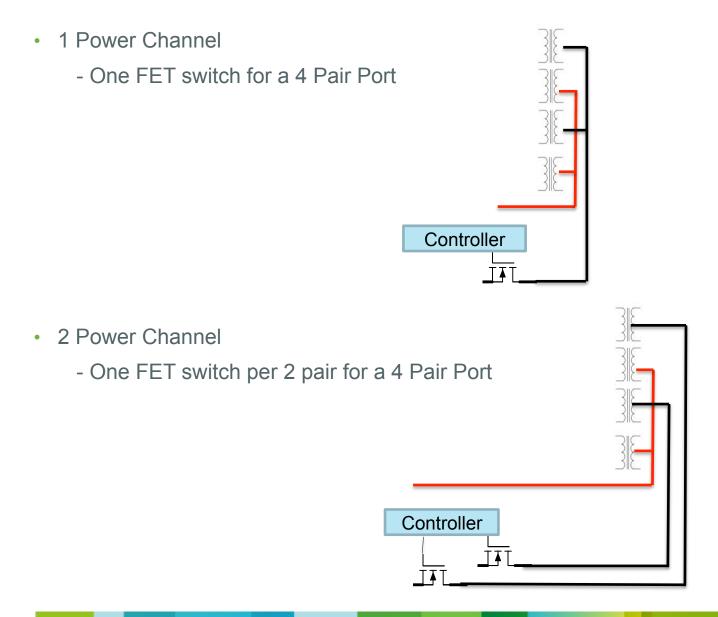
### **Contributors**

- Jean Picard Texas Instruments
- Victor Renteria Belfuse Inc.
- Farid Hamidy Pulse Electronics
- Ken Coffman Fairchild

### **Supporters**

- Jean Picard Texas Instruments
- Farid Hamidy Pulse Electronics
- Victor Renteria Belfuse Inc.
- Fred Schindler Seen Simply
- Miklos Lukacs Silicon Laboratories
- David Tremblay Hewlett Packard
- Leonard Stencel Bourns
- Yair Darshan MircroSemi
- Rick Frosch Phihong
- Yakov Belopolsky Bel Stewart Connector
- Ken Coffman Fairchild

# Terminology



# **System Development & Deployment Costs**

- PoE subsystem cost consists of 3 elements:
- 1. Material Costs

PCB, Power suppl(ies), RJ45+Magnetics, Port Controller IC, Per-Port Discretes, I2C Bus Isolation

2. Development Costs

Schematic design & component selection Layout: prototyping, system test, refinements Thermal studies

3. Inventory Costs and Marketing/Time-To-Market (TTM) Inventory: carrying costs, taxes, etc.

Marketing (soft costs): opportunity loss if TTM stretches out

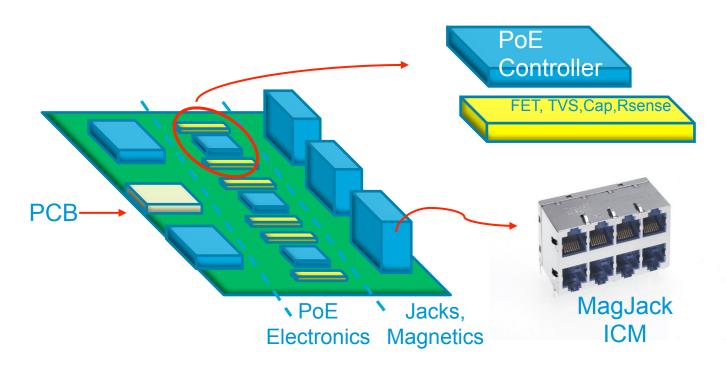
This presentation will focus on Material Cost comparisons between 1 Power Channel and 2 Power Channel implementations

# **PSE Material Cost – Drill Down**

Material Costs

- PCB: multi-layer PCB
- Power suppl(ies)
- RJ45+Magnetics: center-tap capable transformer/injector, extra LED (optional) to indicate PoE is enabled
- Port Controller IC (power manager IC optional)
- Per-Port Discretes: FETs, Rsense, TVS, port cap
- I2C bus isolation: optocoupler or isolation IC

### **PSE Breakout: 24-port 4PPOE Switch Example**

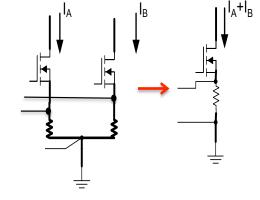


- Costs impacted by the choice of 2-Power Channel vs. 1-Power Channel architectures will be explored using a <u>24 Port Switch Use Case</u>
- The multipliers are compared to a 30W IEEE 802.3-AT base case The multipliers are an estimate since actual prices and volumes vary
- The analysis includes components whose cost vary between the 2 implementations Common components like Power Supply etc., are not included

### PSE Breakout: Controller IC Cost Impact External FET Solution

		Cost Increase	over 30W AT	
PoE Controller	Solution	2-Power Channel	1-Power Channel	Delta Between 1- and 2- Power Channel
	External FET	2x	1.4x	-30%

- 1 Power Channel must support high accuracy ADC
  - 2x dynamic range/Higher SNR results in silicon cost increase
    - A larger dynamic range puts more stress on analog circuit design to meet accuracy requirements.
    - Could also require more complex digital circuitry.
    - Makes it more difficult to implement on low-cost mixed signal process<sup>1</sup>.
- 2-Power Channel
  - Requires two "AT" chip ports per RJ45



#### PSE Breakout: Controller IC Cost Impact Internal FET Solution

	Cost Increa		e over 30W AT	
PoE Controller	Solution		1-Power Channel	Delta Between 1- and 2- Power Channel
	Integrated FET	2x	1.8x	-10%

- 1 Power Channel
  - Silicon Area Increase
    - Major contributing factor for this size increase is the FET
      - Required to keep total power dissipation at acceptable level and match power losses
- 2 Power Channel
  - Requires two "AT" ports per RJ45

### PSE Breakout: Port TVS/Rsense Components Cost Impact

	Cost Increase over 30W			
TVS, Rsense	Component	2-Power Channel	1-Power Channel	Delta between 1- and 2- power channel
	TVS	2x	1x	-50%
	Rsense	2x	3x	+50%

- <u>**TVS**</u>: 2-power channel case requires 1 TVS per 2-pair.
- <u>Rsense</u>: Assumes same sense resistor value (for current measurement accuracy during DC-Disconnect for existing "AT" PDs

2 POWER CHANNEL:	1 POWER CHANNEL:
(for 60W Case)	(for 60W case)
- $P = I^2 R = 0.6*0.6*0.25 = 0.09W^1$	$- P = I^2 R = 1.2 \times 1.2 \times 0.25 = 0.36 W.$
<ul> <li>Including derating <u>0.25W</u> rated sense</li> </ul>	<ul> <li>Including derating <u>1W</u> rated sense would</li> </ul>
would be good	be good
- Sense Resistor Size – <u>0805</u>	- Sense Resistor Size – <u>2512</u>

<sup>1</sup> - We are assuming a simplified model that doesn't cover unbalance.

#### PSE Breakout: Port FET Component Cost Impact

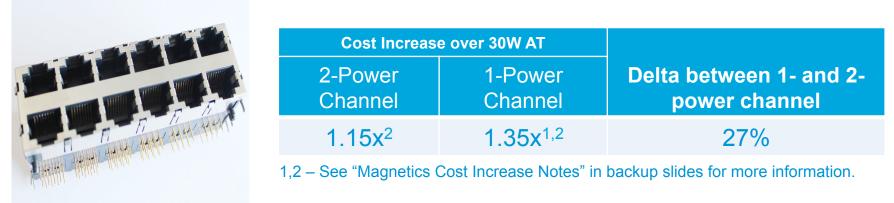
FE	ET	

	Cost Increase	e over 30W AT	
Component	2-Power Channel	1-Power Channel	Delta between 1- and 2-power channel
FET	2x	1.5x	-25%

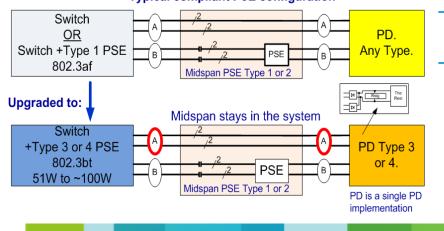
- FET Choice is controlled by two considerations
  - Thermal Dissipation during normal operation
  - SOA (Safe Operating Area)
- Same power dissipation for 2 Power Channel and 1 Power channel assumed

2 POWER CHANNEL:	1 POWER CHANNEL:
<ul> <li>Current per FET = lport/2</li> </ul>	- Current per FET = Iport
- Twice number of FETs per port	- SOA performance for 1 Power channel
	should support higher current compared to 2
	power channel in all situations (including
	Short circuit)
	- FET die Size of 1 power channel = 2 X FET
	die size of 2 power channel → Cost Impact

# **PSE Breakout: Magnetics/Jack Cost Impact**



	OWER CHANNEL: Independent control over each 2pair	<u>1 POWER CHANNEL:</u> - Has no independent control over each of the 2pair
-	Worst case current per 2 Pair magnetics = lport/2	- Worst case current per 2 pair magnetics = lport (refer to picture below)
	magnetics – iport/2	- To avoid damage, bigger Magnetics needed to handle
		higher current → Cost Increase



#### Typical compliant PoE configuration

# When there is a 2-pair mid span and 4-pair end span connected to same PD:

- If end span wins the arbitration:
  - 1 power channel: all power will be provided on one 2-pair.
  - For example, if PD draws 60W → all of this is provided over 2-pair (1.2A over 2-pair Magjack as opposed to 0.6A).

# **PSE Breakout: PCB Cost Impact**



Thermal Dissipation needs drive increased cost

- Using the 1-power channel approach instead of the 2-power channel approach introduces additional dissipation

- For a group of 24 ports operating at high power (60W PSE output):
  - 1-Power channel has 2X dissipation compared to 2-Power channel
    - Since the Rsense choice is same between 2-Power and 1-Power channel to provide accuracy
  - Multiple GND planes, thicker copper (ex: 2 ounces) per layer.
  - Larger board area is needed for same number of ports.
  - Maximum number of high power ports per unit of PCB area is lower

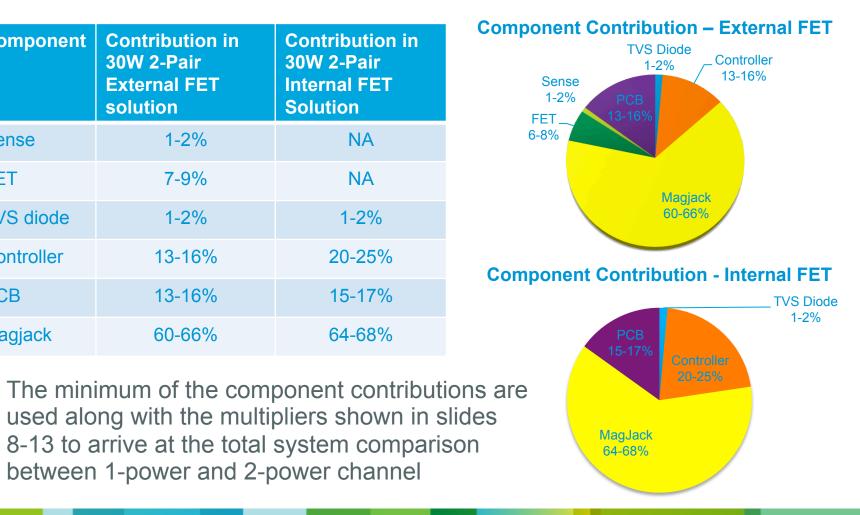
# **PSE System Comparison: Component Cost Weighting**

- Not all components contribute equally towards system cost •
- Contribution in a typical base system of 2Pair 30W is shown •
  - These percentages were taken from a variety of sources and vendors; thus ranges are given for each component

Component	Contribution in 30W 2-Pair External FET solution	Contribution in 30W 2-Pair Internal FET Solution
Sense	1-2%	NA
FET	7-9%	NA
TVS diode	1-2%	1-2%
Controller	13-16%	20-25%
PCB	13-16%	15-17%
Magjack	60-66%	64-68%

between 1-power and 2-power channel

•



#### **PSE Breakout: Cost Comparison Summary** External FET Solution

• Taking into consideration the weighting of the various components, the data shows that when building a 60W system using external FETs:

The 2-Power Channel architecture is approximately 2% less costly than the 1-Power Channel architecture.

 $\Delta = 1 - 1 + Dual Power Channel Cost Increase/1 + Single Power Channel Cost Increase = 1 - 1 + 0.34/1 + 0.37 = 0.02$ 

		Dual Pov	wer Channel	Single Power Channel	
Component	Weighting	Increase over AT*	Effective Contribution	Increase over AT*	Effective Contribution
Magjack	61.0%	15.0%	9.15%	35.0%	21.35%
PCB	14.0%	0.0%	0.00%	20.0%	2.80%
PoE Controller	14.0%	100.0%	14.00%	40.0%	5.60%
FET	8.0%	100.0%	8.00%	50.0%	4.00%
Sense Resistor	1.5%	100.0%	1.50%	200.0%	3.00%
TVS Diode	1.5%	100.0%	1.50%	0.0%	0.00%
Total Cost Increase			<b>34.15%</b> ared to a 30W AT sys		36.75%

#### PSE Breakout: Cost Comparison Summary Internal FET Solution

• Taking into consideration the weighting of the various components, the data shows that when building a 60W system using external FETs:

The 2-Power Channel architecture is approximately 7% less costly than the 1-Power Channel architecture.

 $\Delta = 1 - 1 + Dual Power Channel Cost Increase/1 + Single Power Channel Cost Increase = 1 - 1 + 0.31/1 + 0.41 = 0.07$ 

		Dual Pov	wer Channel	Single Po	wer Channel
Component	Weighting	Increase over AT*	Effective Contribution	Increase over AT*	Effective Contribution
Magjack	64.0%	15.0%	9.60%	35.0%	22.40%
PCB	15.0%	0.0%	0.00%	20.0%	3.00%
PoE Controller	20.0%	100.0%	20.00%	80.0%	16.00%
TVS Diode	1.0%	100.0%	1.00%	0.0%	0.00%
Total Cost Increase			30.60%		41.40%

\* Cost increase indicated is for a 60W system compared to a 30W AT system.

# **Further Cost Considerations**

- The numbers reported in this presentation are very conservative and the cost advantage of the 2-power channel architecture is probably greater than shown here.
- In addition, these factors have not been included in the previous analysis:
  - 2-Power Channel
  - The indirect savings that come from lower power dissipation (sense resistor, slide 6)
  - There is volume advantage as it can use parts available today
  - 1- Power channel
  - Includes only PSE side magjack cost increase
    - PD side will also need larger jack magnetics leading to increased cost
  - Cost increase for 100W case will be more and non linear increase vs. 60W case

# Summary

- Magnetics are the main contribution to system cost (more than 60%)
  - 1-Power channel approach's magnetics are 20% higher than 2-Power channel
  - PoE controller cost contribution is much less than magnetics contribution
- Conclusion:
  - The data in this presentation affirms, 2-power channel is not twice as costly as 1 power channel. The costs are very comparable and in some cases that 2 Power channel implementations are less costly than 1 Power channel implementations

Backup

# **Magnetics Cost Increase Notes**

• Note 1:

This is an extremely conservative number for the following reasons:

- Assumes bigger magnetics only on ALT- A pair in order to handle the midspan case.
- Cost will increase even more if normal wire faults are considered where ALT-A or ALT-B both could be carrying full port current.
- This increase is the cost associated with preventing damage to the magnetics (not ensuring operation).
- The above cost increase is for 60W. Cost increase as we move to 100W will not be linear.
- In addition, this does not include cost increase due to PD side magnetics.
- Note 2:

Bringing out the extra center-taps drives a cost increase for both 1-power channel and 2-power channel implementations.

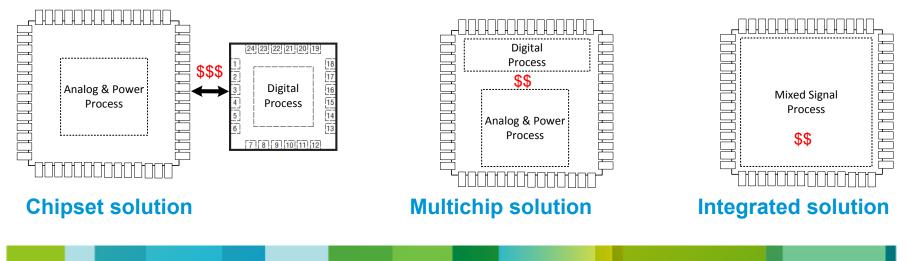
#### Impact of Doubling the Current Sensing Dynamic Range Beyond what is done Today

• Solutions could be:

Use 2 separate chips (maybe 2 separate devices) and different silicon process (each one optimized for analog or digital), which means much higher cost.

If single-chip solution: use a different process and/or larger/more expensive die to meet analog accuracy requirement.

- In all cases, there will be significant cost increase.
- Also consider that some manufacturers have capability to do multi-chip while others don't, or can do it at much higher costs.



### **PSE Breakout: Cost Comparison Summary** External FET Solution<sup>1</sup>

		0W system compared 80W system	d Reasons for Cost Increase compared to 30W	
Component	2-Power Channel	1-Power Channel	IEEE802.3AT system	
TVS diode	100%	0%	2 Power Channel : Twice number of Diodes	
			2 Power Channel: Twice number of chips	
PoE Controller	100.00%	30-50%	1 Power Channel: Silicon Area increase	
			2 Power Channel: Extra center tap access	
			1 Power Channel: Extra center tap access + bigger	
Magjack	15.00%	30-40%	Magjack capable of carrying all current in one 2pair <sup>2</sup>	
			2 Power Channel: Twice number of FETs	
FET	100.00%	50.00%	1 Power Channel: Bigger FET to carry all current	
			2 Power Channel: Twice number of resistors	
			1 Power Channel: Bigger Sense Resistor – 4X Power rating	
Sense	100.00%	200.00%	compared to 2 Power channel	
			1 Power channel: More thermal relief needed due to	
РСВ	0.00%	20.00%	increased dissipation	

<sup>1</sup> For 2 power channel solution, there is a volume advantage as it can use parts available today – The above table does not reflect this additional cost benefit

<sup>2</sup> Includes only PSE side magjack cost increase. Note PD side will also need bigger magjack  $\rightarrow$  More cost Shows only 60W case – Cost increase for 100W case will be more and non linear increase

Assumes bigger magnetics only on ALT- A pair  $\rightarrow$  to handle the midspan case

Cost will increase even more if normal wire faults are considered where ALT-A or ALT-B both could be carrying full port current



#### **PSE Breakout: Cost Comparison Summary** Internal FET Solution<sup>1</sup>

	Cost Increase of a 60W system compared to an AT 30W system		Reasons for Cost Increase compared to 30W
Component	2-Power Channel	1-Power Channel	IEEE802.3AT system
TVS diode	100.00%	0%	2 Power Channel : Twice number of Diodes
PoE Controller	100.00%	80%	2 Power Channel: Twice number of chips 1 Power Channel: Silicon area increase
Magjack	15.00%	30-40%	2 Power Channel: Extra center tap access 1 Power Channel: Extra center tap access + bigger Magjack capable of carrying all current in one 2pair <sup>2</sup>
РСВ	0%	20.00%	1 Power channel: More thermal relief needed due to increased dissipation

<sup>1</sup> For 2 power channel solution, there is a volume advantage as it can use parts available today – The above table doesn't include this cost benefit

<sup>2</sup> Includes only PSE side magjack cost increase. Note PD side will also need bigger magjack → More cost Shows only 60W case – Cost increase for 100W case will be more and non linear increase

# **Discrete Magnetics – External FET**

Component	Weighting	2- Power Channel		1-Power Channel	
		Increase over AT	Effective contribution	Increase over AT	Effective Contribution
Discrete magnetics	50%	15%	7.5%	35%	17.5%
PCB	21%	0%	0%	20%	4.2%
PoE Controller	17%	100%	17%	40%	6.8%
FET	8%	100%	8%	50%	4%
Sense Resistor	2%	100%	2%	200%	4%
TVS diode	2%	100%	2%	0%	0%
TOTAL COST INCREASE			36.5%		36.5%

# **Discrete Magnetics – Internal FET**

Component	Weighting	2- Power Channel		1-Power Channel	
		Increase over AT	Effective contribution	Increase over AT	Effective Contribution
Discrete magnetics	53%	15%	7.95%	35%	18.55%
PCB	24%	0%	0%	20%	4.2%
PoE Controller	21%	100%	24%	80%	19.20%
TVS diode	2%	100%	2%	0%	0%
TOTAL COST INCREASE			33.95%		41.95%

